

Listing of Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

1. (Previously Presented) A package for a semiconductor device comprising:
a semiconductor die having a laterally conducting structure and a ground contact
on an upper surface; and
a leadframe comprising,
a diepad in contact with a lower surface of the die,
a lead separated from the diepad, and
a supplemental downbond diepad portion projecting from a main portion
of the diepad and configured to receive a downbond wire from the ground contact, the
supplemental diepad portion positioned between an end of the package and the die, and
immediately between the lead and a second lead that is also separate from the diepad.
- 2-4. (Canceled)
5. (Original) The package of claim 1 comprising more than one supplemental
downbond portion.
6. (Original) The package of claim 1 wherein the die comprises a power IC die.
7. (Original) The package of claim 1 wherein the die is configured to operate
with a current of between about 1 and 20 Amps.
8. (Original) The package of claim 1 wherein the die is selected from the group
consisting of an integrated circuit, a JFET, and a lateral MOSFET.
9. (Original) The package of claim 1 wherein the diepad comprises copper.
- 10.-16 (Canceled)